

**VOLTAGE RANGE: 30 - 60V**  
**CURRENT: 3.0 A**

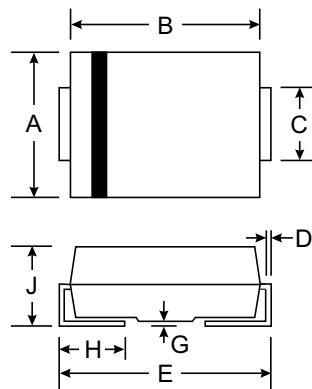
### Features

- For Surface Mounted Applications
- High Temperature Metallurgically Bonded Contacts
- Plastic Material - UL Flammability
- Classification 94V-0
- High Reliability
- High Current Capability and Low VF  
Submersible Temperature of 265°C for 10 Seconds in Solder Bath



### Mechanical Data

- Case: SMA(DO-214AC), Molded Plastic
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Mounting Position: Any
- Weight: 0.064 grams (approx.)



SMA(DO-214AC)		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.10	0.20
H	0.76	1.52
J	2.01	2.62
All Dimensions in mm		

### Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise specified

Characteristic	Symbol	15MQ030NPBF	15MQ040NPBF	15MQ060NPBF	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	30	40	60	V
Working Peak Reverse Voltage	V <sub>RWM</sub>				
DC Blocking Voltage	V <sub>R</sub>				
RMS Reverse Voltage	V <sub>R(RMS)</sub>	21	28	42	V
Average Rectified Output Current @T <sub>L</sub> = 105°C	I <sub>O</sub>	3.0			A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	80			A
Forward Voltage @I <sub>F</sub> = 3.0A	V <sub>FM</sub>	0.50		0.70	V
Peak Reverse Current @T <sub>A</sub> = 25°C At Rated DC Blocking Voltage @T <sub>A</sub> = 100°C	I <sub>RM</sub>	1.0 20			mA
Typical Thermal Resistance (Note 1)	R <sub>θJL</sub> R <sub>θJA</sub>	10 50			°C/W
Operating Temperature Range	T <sub>J</sub>	-65 to +125			°C
Storage Temperature Range	T <sub>STG</sub>	-65 to +150			°C

Note: 1. Mounted on P.C. Board with 8.0mm<sup>2</sup> copper pad area.

FIG. 1 - FORWARD CURRENT DERATING CURVE

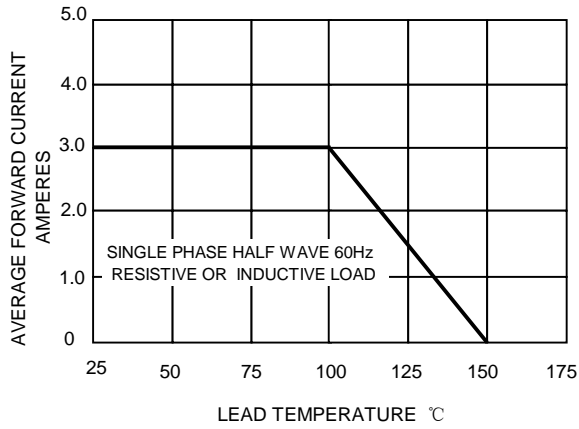


FIG.2 - MAXIMUM NON-REPETITIVE SURGE CURRENT

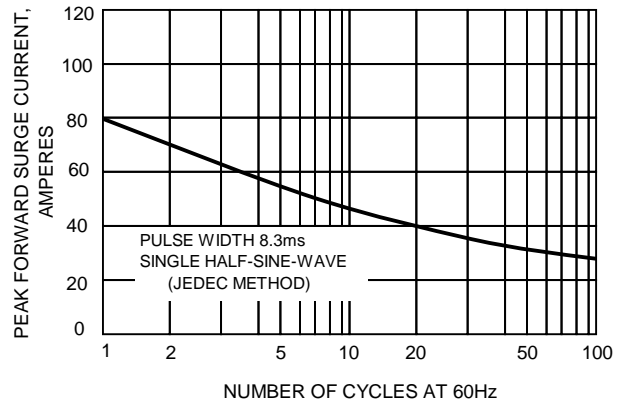


FIG.3-TYPICAL FORWARD CHARACTERISTICS

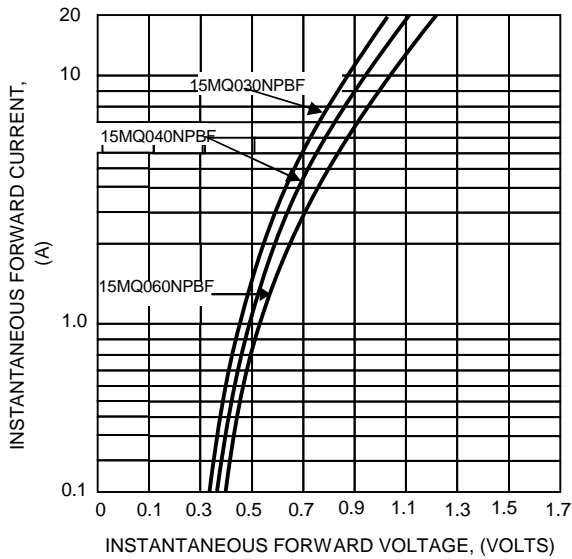


FIG.4-TYPICAL JUNCTION CAPACITANCE

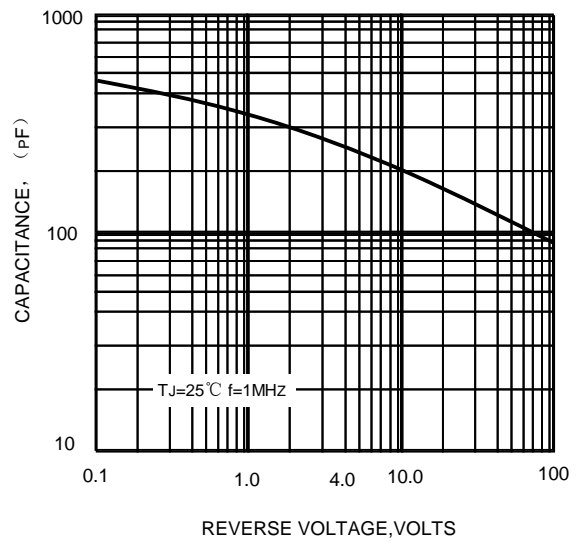


FIG.5-TYPICAL REVERSE CHARACTERISTICS

